

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1–20. (Cancelled)

21. (Currently Amended) Standard micro-component for calibrating and standardizing fluorescence measuring instruments ~~comprising~~ comprising:

~~a substrate whereon there is arranged at least one thin layer comprising fluorescent components, said micro-component comprising the at least one thin layer including~~ at least first and second fluorescence levels, ~~micro-component wherein~~ the first and second fluorescence levels ~~are being~~ respectively defined by a non-exposed part and by at least one exposed zone of said thin layer, the second fluorescence level being lower than the first fluorescence level.

22. (Original) Standard micro-component according to claim 21, wherein the thin layer comprises at least one opening defining a third fluorescence level lower than the first and second fluorescence levels.

23. (Original) Standard micro-component according to claim 22, wherein the third fluorescence level corresponds to the fluorescence level of the substrate.

24. (Original) Standard micro-component according to claim 22, wherein the third fluorescence level is at least 10 times lower than the first fluorescence level.

25. (Original) Standard micro-component according to claim 24, wherein the third fluorescence level is at least 100 times lower than the first fluorescence level.

26. (Original) Standard micro-component according to claim 21, wherein the thin layer is formed by a fluorescent material.

27. (Original) Standard micro-component according to claim 21, wherein the thin layer comprises a plurality of exposed zones so as to define a plurality of different fluorescence levels.

28. (Original) Standard micro-component according to claim 21, wherein the thin layer is formed by a photosensitive resin.

29. (Original) Standard micro-component according to claim 21, wherein the substrate is formed by a material selected from the group consisting of silicon, synthetic silica, quartz, plastics and glasses.

30. (Original) Standard micro-component according to claim 21, wherein at least a part of the thin layer is covered by a protective thin layer.

31. (Original) Standard micro-component according to claim 30, wherein the protective thin layer is transparent to optical reading signals received and sent back by the thin layer.

32. (Original) Standard micro-component according to claim 30, wherein the micro-component comprises a plurality of stacked protective thin layers.

33. (Original) Standard micro-component according to claim 30, wherein the material forming the protective thin layer is selected from the group consisting of the following materials: TiO₂, Ta₂O₅, HfO₂, ZrO₂, MgO, SiO₂, Si₃N₄, MgF₂, YF₃, Al₂O₃, ZrO₄Ti, Y₂O₃, diamond and oxynitrides.

34. (Original) Standard micro-component according to claim 30, wherein the thickness of the protective thin layer is calculated using the following formula: n.e = kλ/ 4, in which n is the refractive index of the material composing the protective thin layer for a wavelength λ of the optical reading signal received by the thin layer, e is the optical thickness of the protective thin layer and k is an odd integer.

35. (Original) Standard micro-component according to claim 21, wherein the standard micro-component comprises a plurality of stacked thin layers so as to define a plurality of fluorescence levels.

36. (Original) Standard micro-component according to claim 35, wherein the openings of at least two thin layers are superposed.

37. (Original) Biochip comprising, on a single substrate, at least one biological sensor and at least one standard micro-component according to claim 21.

38. (Currently Amended) Fabrication process of a standard micro-component according to claim 21, comprising comprising:

_____ deposition on a substrate of at least one thin layer comprising fluorescent components, ~~process consisting in~~

_____ exposing at least one zone of the thin layer so that first and second fluorescence levels are respectively defined by the non-exposed part and by the exposed zone of the thin layer.

39. (Original) Fabrication process of a standard micro-component according to claim 38, comprising deposition, on the substrate, of a plurality of stacked thin layers.

40. (Original) Fabrication process of a standard micro-component according to claim 38, comprising deposition of a protective thin layer after exposure.